



HG15N120F1A

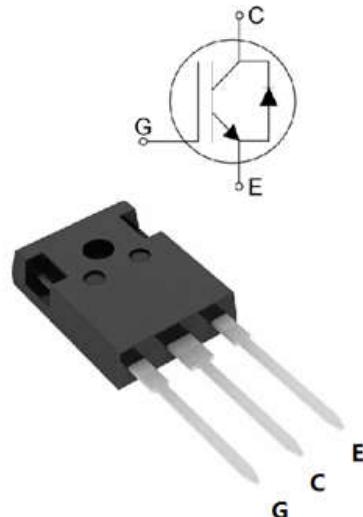
1200V/15A Trench Field Stop IGBT

Lu-semi Field Stop Trench IGBTs offer low switching losses, high energy efficiency and high avalanche ruggedness for soft switching applications such as inductive heating, microwave oven, etc.

V _{CE}	1200	V
I _C	15	A
V _{CE(SAT)} I _C =15A	1.9	V

FEATURES

- Trench-Stop Technology offering :
 - High speed switching
 - High ruggedness, temperature stable
 - Low V_{CEsat}
 - Easy parallel switching capability due to positive temperature coefficient in V_{CEsat}
- Soft current turn-off waveforms
- Enhanced avalanche capability



APPLICATION

- Inductive cooking
- Inverterized microwave ovens
- Resonant converters
- Soft switching applications

Product	Package	Packaging
HG15N120F1A	TO247	Tube



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Maximum Ratings

Parameter	Symbol	Value	Unit
Collector-Emitter Breakdown Voltage	V_{CE}	1200	V
DC collector current, limited by T_{jmax} $T_C = 25^\circ C$ $T_C = 100^\circ C$	I_C	30 15	A
Diode Forward current, limited by T_{jmax} $T_C = 25^\circ C$ $T_C = 100^\circ C$	I_F	30 15	A
Continuous Gate-emitter voltage	V_{GE}	± 20	V
Transient Gate-emitter voltage	V_{GE}	± 30	V
Turn off safe operating area $V_{CE} \leq 1200V$, $T_j \leq 150^\circ C$	-	45	A
Pulsed collector current, $V_{GE}=15V$, t_p limited by T_{jmax}	I_{CM}	45	A
Power dissipation , $T_j=25^\circ C$	P_{tot}	260	W
Operating junction temperature	T_j	-40...+150	°C
Storage temperature	T_s	-55...+150	°C
Soldering temperature, wave soldering 1.6mm (0.063in.) from case for 10s	-	260	°C

Thermal Resistance

Parameter	Symbol	Max. Value	Unit
IGBT thermal resistance, junction - case	$R_\theta(j-c)$	0.7	K/W
Diode thermal resistance, junction - case	$R_\theta(j-c)$	1.5	K/W
Thermal resistance, junction - ambient	$R_\theta(j-a)$	40	K/W



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Electrical Characteristics of the IGBT (T_j= 25°C unless otherwise specified) :

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Static						
Collector-Emitter breakdown voltage	BV _{CES}	V _{GE} =0V , I _C =250μA	1200	-	-	V
Gate threshold voltage	V _{GE(th)}	V _{GE} =V _{CE} , I _C =250μA	5.2	5.8	6.8	V
Collector-Emitter Saturation voltage	V _{CE(sat)}	V _{GE} =15V, I _C =15A T _j = 25°C T _j = 150°C	- -	1.9 2.3	2.3	V
Zero gate voltage collector current	I _{CES}	V _{CE} = 1200V, V _{GE} = 0V T _j = 25°C T _j = 150°C	- -	-	100 1000	μA
Gate-emitter leakage current	I _{GES}	V _{CE} = 0V, V _{GE} = ±20V	-	-	100	nA
Transconductance	g _f s	V _{CE} = 20V, I _C = 15A	-	10	-	S

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Dynamic						
Input capacitance	C _{ies}	V _{CE} = 25V, V _{GE} = 0V, f = 1MHz	-	1520	-	pF
Output capacitance	C _{oes}		-	52	-	
Reverse transfer capacitance	C _{res}		-	30	-	
Gate charge	Q _G	V _{CC} = 960V, I _C = 15A, V _{GE} = 15V	-	84	-	nC



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Switching Characteristic, Inductive Load

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Dynamic , at $T_j = 25^\circ C$						
Turn-on delay Time	$t_{d(on)}$	$V_{CC} = 600V, I_C = 15A,$ $V_{GE} = 0/15V,$ $R_g=12\Omega$	-	24	-	ns
Rise Time	t_r		-	17	-	ns
Turn-off delay time	$t_{d(off)}$		-	80	-	ns
Fall time	t_f		-	79	-	ns
Turn-on Energy	E_{on}			1.57	-	mJ
Turn-off energy	E_{off}		-	0.28	-	mJ

Electrical Characteristics of the DIODE ($T_j = 25^\circ C$ unless otherwise specified)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Dynamic						
Diode Forward Voltage	V_{FM}	$I_F = 15A$ $I_F = 10A,$ $di/dt = 200A/\mu s$	-	2.3	-	V
Reverse Recovery Time	T_{rr}		-	70	-	ns
Reverse Recovery Current	I_{rr}		-	5	-	A
Reverse Recovery Charge	Q_{rr}		-	1600	-	nC

Fig. 1 FBSOA characteristics

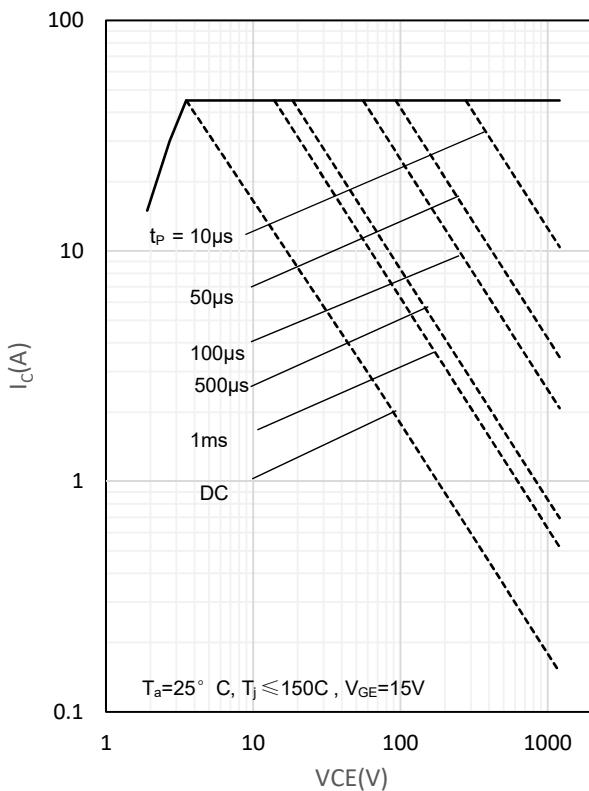


Fig. 2 Load Current vs. Frequency

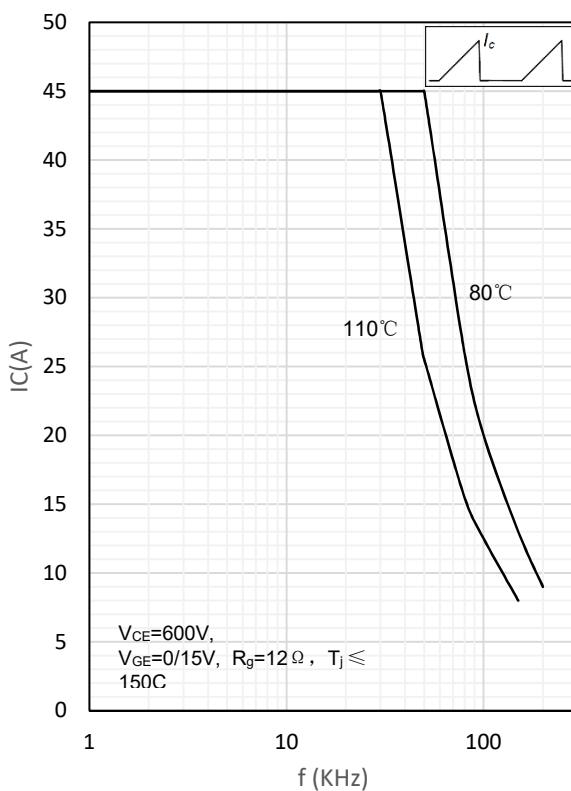


Fig. 3 Output characteristics

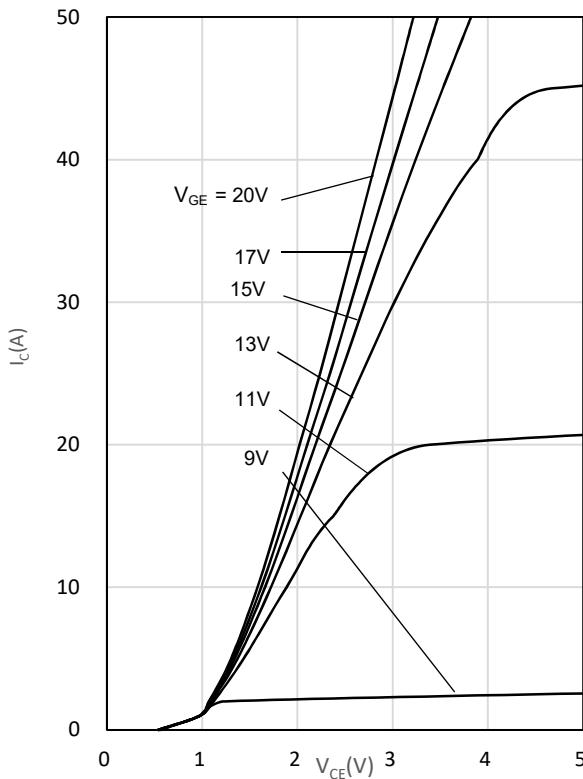


Fig. 4 Saturation voltage characteristics

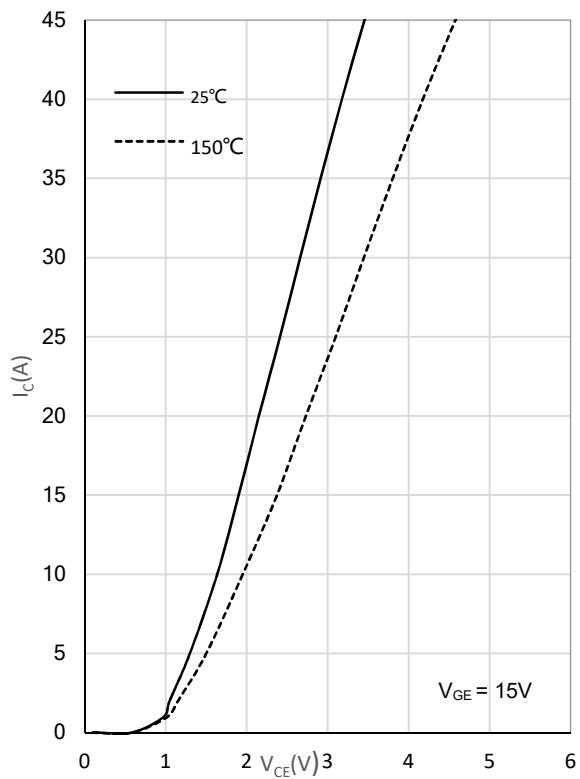


Fig. 5 Switching times vs. gate resistor

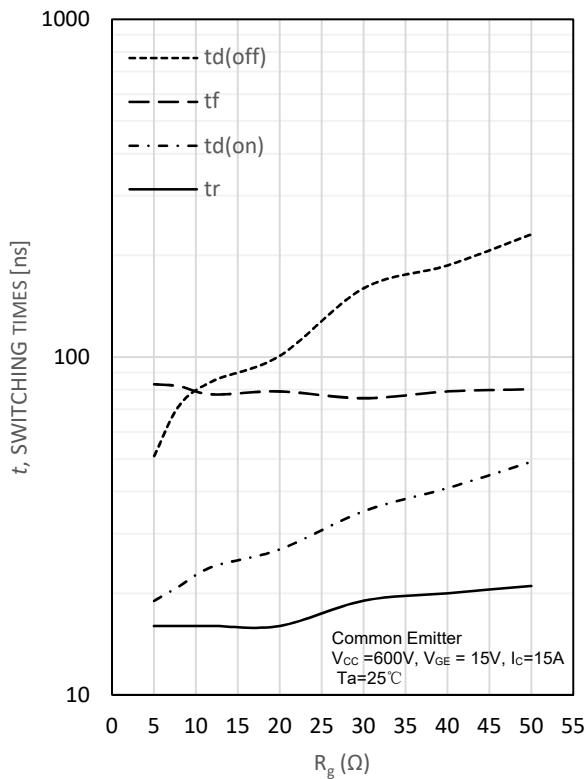


Fig. 6 Switching times vs. collector current

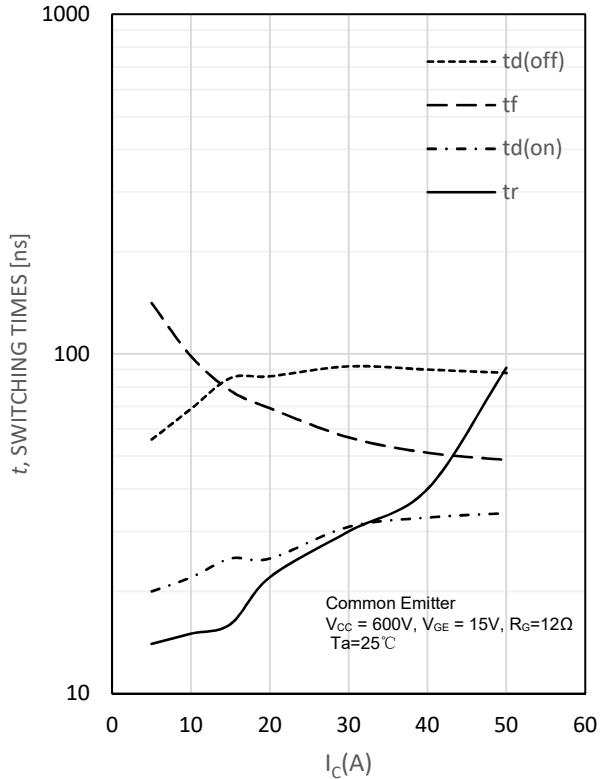


Fig. 7 Switching loss vs. gate resistor

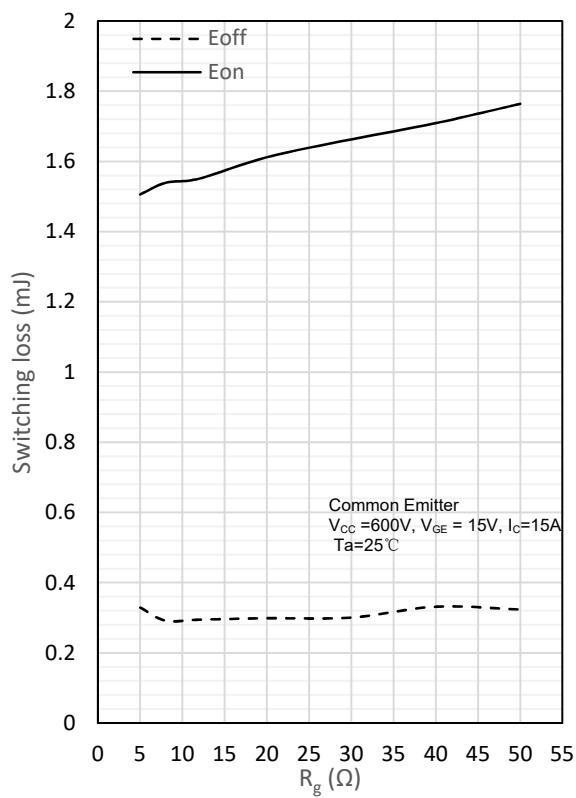


Fig. 8 Switching loss vs. collector current

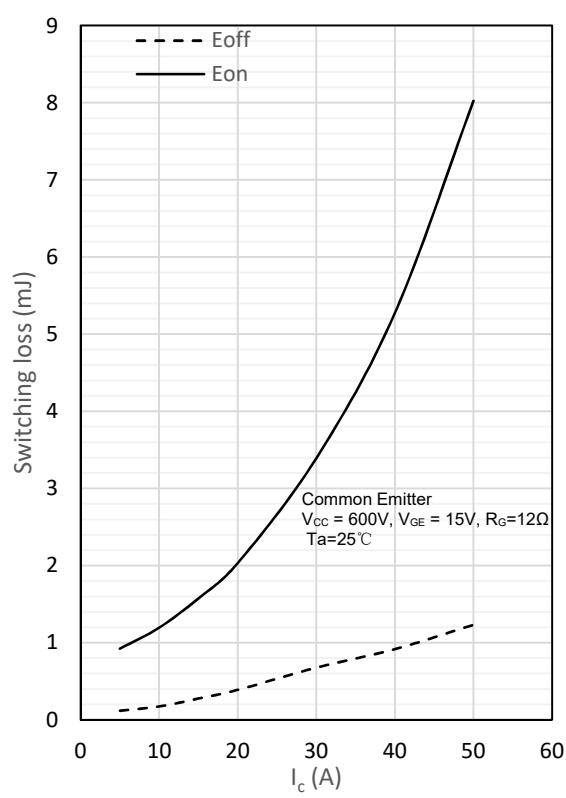
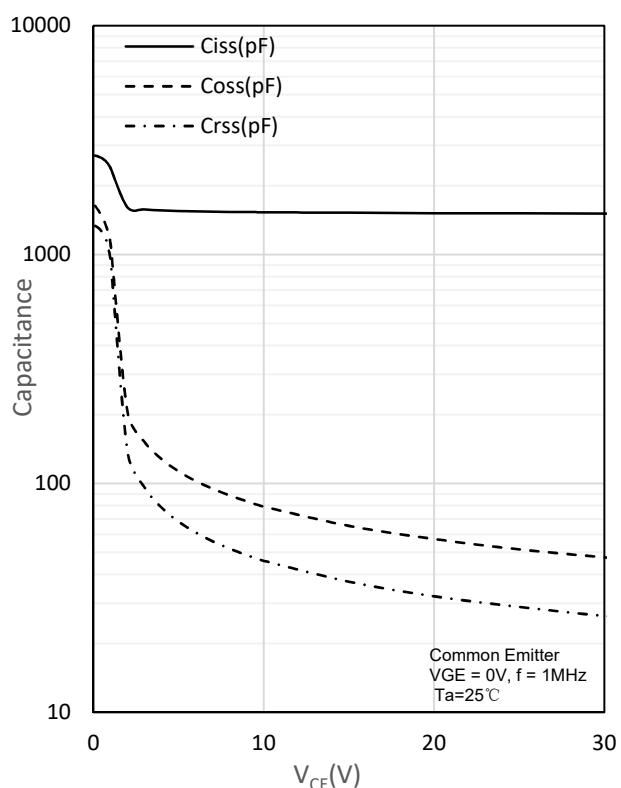
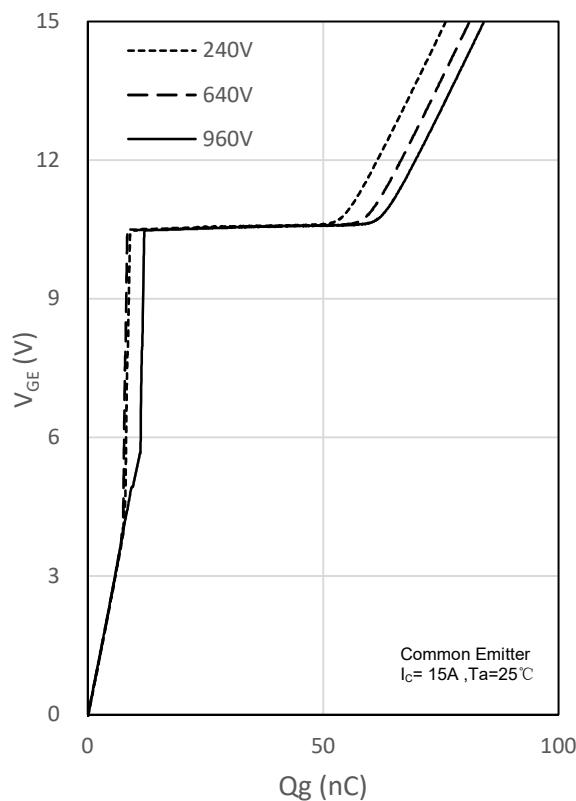
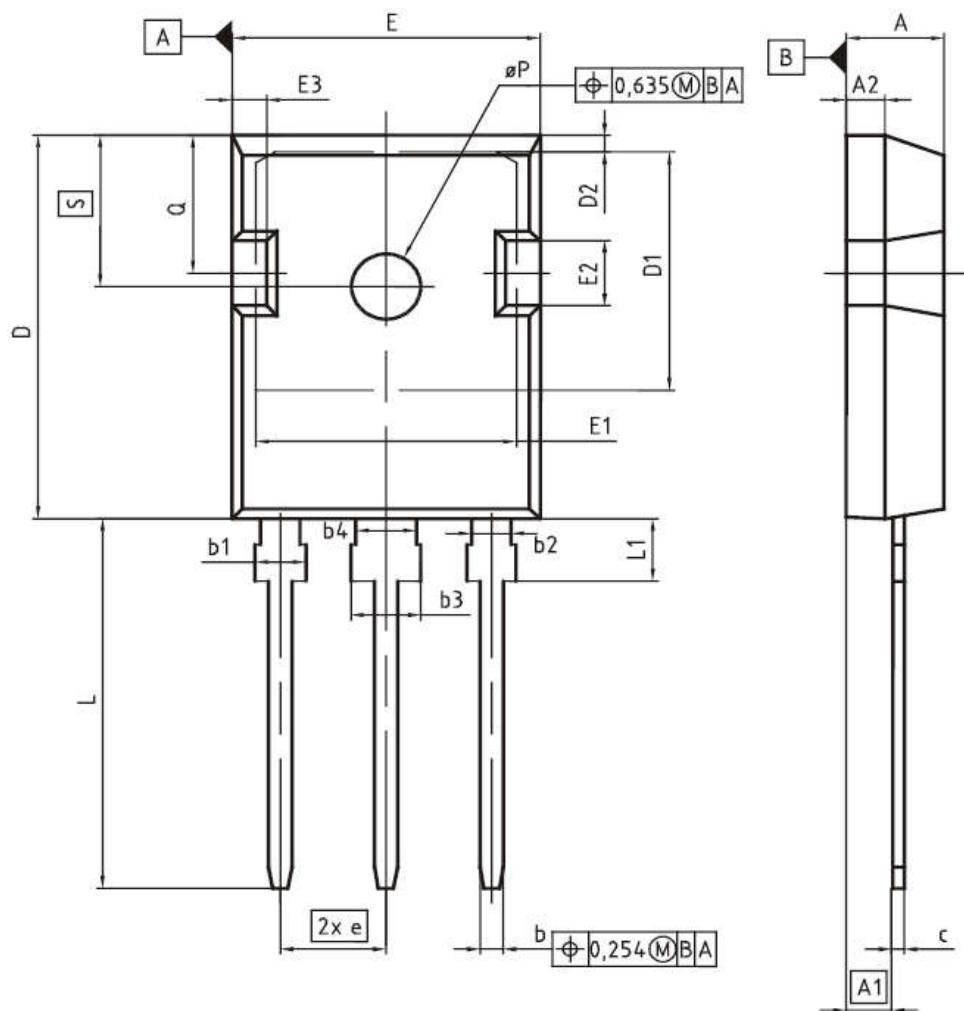


Fig. 9 Gate charge characteristics

Fig. 10 Capacitance characteristics



PG-T0247-3



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.83	5.21	0.190	0.205
A1	2.27	2.54	0.089	0.100
A2	1.85	2.16	0.073	0.085
b	1.07	1.33	0.042	0.052
b1	1.90	2.41	0.075	0.095
b2	1.90	2.16	0.075	0.085
b3	2.87	3.38	0.113	0.133
b4	2.87	3.13	0.113	0.123
c	0.55	0.68	0.022	0.027
D	20.80	21.10	0.819	0.831
D1	16.25	17.65	0.640	0.695
D2	0.95	1.35	0.037	0.053
E	15.70	16.13	0.618	0.635
E1	13.10	14.15	0.516	0.557
E2	3.68	5.10	0.145	0.201
E3	1.00	2.60	0.039	0.102
e	5.44 (BSC)		0.214 (BSC)	
N	3		3	
L	19.80	20.32	0.780	0.800
L1	4.10	4.47	0.161	0.176
øP	3.50	3.70	0.138	0.146
Q	5.49	6.00	0.216	0.236
S	6.04	6.30	0.238	0.248